



# Material Composition Declaration

## EPC2304

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2024/11/1
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	31.5 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	9.8217	31.1492	32.4997	311492
	Silicon oxide	7631-86-9	0.0684	0.2170		2170
	Silicon nitride	12033-89-5	0.0477	0.1511		1511
	Gallium nitride	25617-97-4	0.0995	0.3157		3157
	Aluminum	7429-90-5	0.0248	0.0788		788
	Aluminum nitride	24304-00-5	0.0234	0.0741		741
	Titanium	7440-32-6	0.0021	0.0066		66
	Titanium nitride	25583-20-4	0.0118	0.0373		373
	Copper	7440-50-8	0.0004	0.0013		13
	Tungsten	7440-33-7	0.0100	0.0316		316
	Polyimide		0.1378	0.4371	4371	
Under Bump Metal	Titanium	7440-32-6	0.0010	0.0031	0.0337	31
	Copper	7440-50-8	0.0097	0.0306		306
Solder Bump	Copper	7440-50-8	0.8115	2.5736	3.5165	25736
	Nickel	7440-02-0	0.0576	0.1828		1828
	Tin	7440-31-5	0.2354	0.7465		7465
	Silver	7440-22-4	0.0043	0.0137		137
Package	Copper	7440-50-8	11.7262	37.1892	63.9501	371892
	Iron	7439-89-6	0.3007	0.9536		9536
	Mold Compound		7.4515	23.6320		236320
	Tin	7440-31-5	0.6859	2.1754		21754
Sum in total:			31.5313	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.